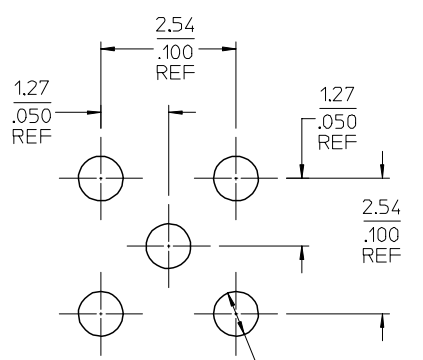
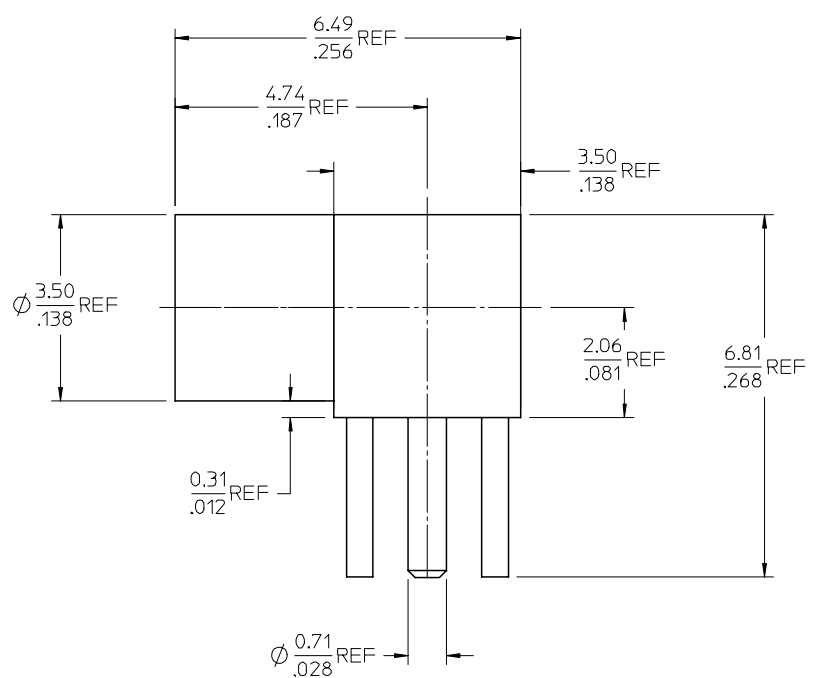
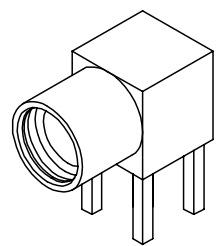


MATERIALS AND FINISHES

BODY BRASS  
PLATED GOLD

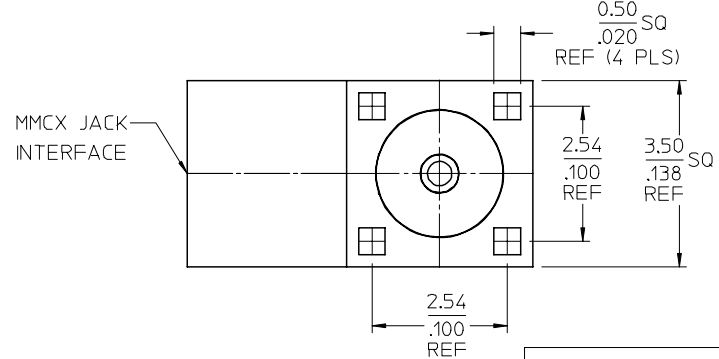
CENTER CONTACT BERYLLIUM COPPER  
PLATED GOLD

INSULATOR TEFLON



RECOMMENDED  
PCB LAYOUT

5 PLACES  
 $\phi 0.84 \pm 0.05$   
 $\phi 0.33 \pm .002$



ES-73599-0000-016	INTERFACE
SPECIFICATION	DESCRIPTION

73415-1001	PER COMMERCIAL REQUIREMENTS
73415-1000	PER MILITARY REQUIREMENTS
PART NUMBER	PLATING

UNLESS OTHERWISE SPECIFIED DIMS ARE MILLIMETERS AND ANGLES ARE DEGREES.

- $\sqrt{R}$  ALL OVER.
- NO CHATTER OR NON-UNIFORM SURFACE FINISH ALLOWED.
- PARTS TO BE FREE OF BURRS & SHARP EDGES 0.13(0.005) MAX BREAK.
- EXTERNAL THREADS TO BE ROLLED OR SINGLE POINT.
- DIAMETERS TO BE CONCENTRIC WITHIN 0.08(0.003) TIR.

CHG: MODIFIED REAR INSULATOR  
EC NO: URF2006-03556  
DRAWN: JMASTRANO 2006/02/10  
CHKD: JMASTRANO 2006/02/10  
APPR: JIMENER 2006/02/10

QUALITY SYMBOLS	
$\nabla=0$	
$\nabla=0$	
GENERAL TOLERANCES (UNLESS SPECIFIED)	
4 PLACES	$\pm$ ----
3 PLACES	$\pm$ ----
2 PLACES	$\pm$ ----
1 PLACE	$\pm$ ----
ANGULAR $\pm 2^\circ$	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

DIMENSION STYLE	
MM/IN	
DRAWN BY	DATE
JM	2005/07/22
CHECKED BY	DATE
JM	2005/07/22
APPROVED BY	DATE
JDW	2005/07/22
MATERIAL NO.	DOCUMENT NO.
SEE TABLE	SD-73415-100

SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	METRIC	$\odot$ $\square$
MMCX JACK, R/A, PCB 50 OHMS MMCX-J/PCB		
MOLEX INCORPORATED		
SHEET NO.	1 OF 1	